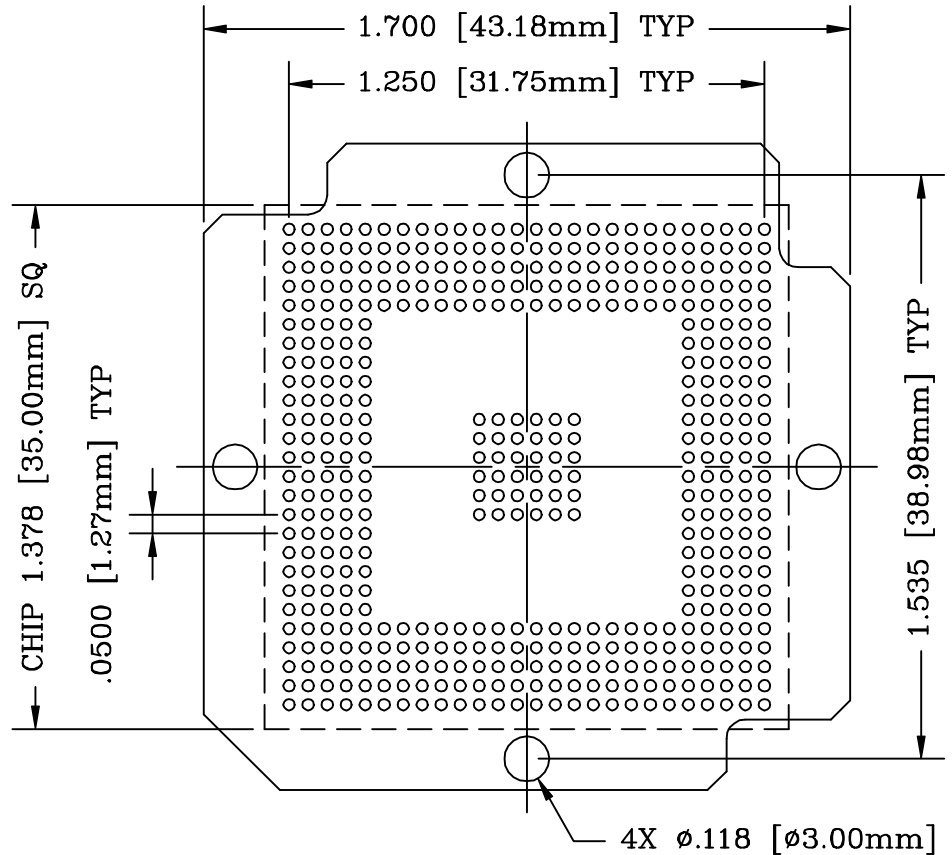
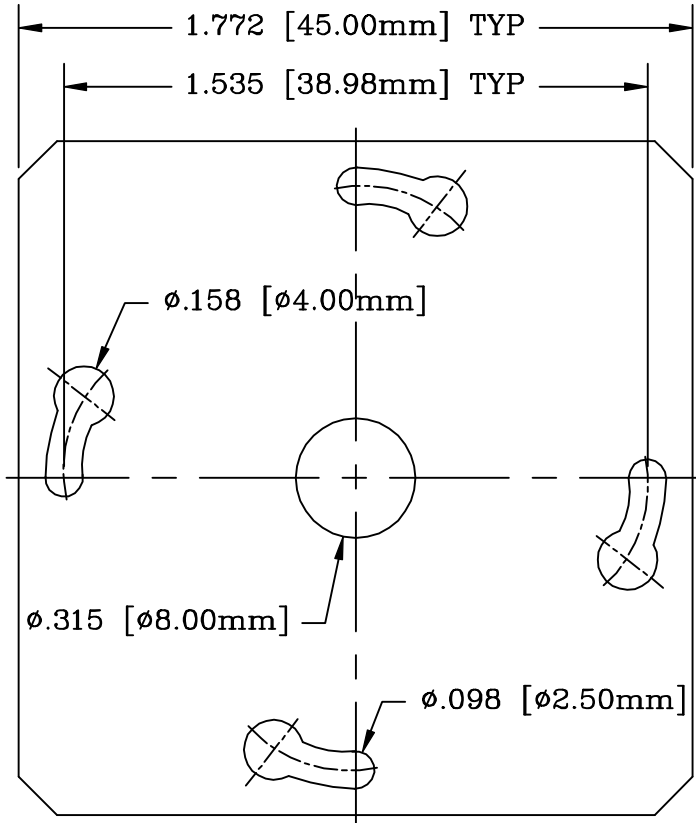


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	04/04/03	H.N.

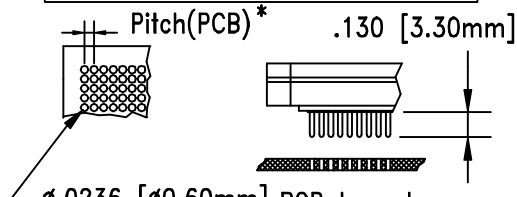
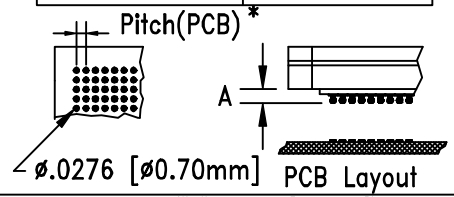
SKT1732
DOD 41732



RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE	RAISED SMT STYLE
XX = (-SM)	XX = (-RC)
YY = (-30)	YY = (-29)

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET)
YY = (-70)



30= standard SMD ("A" = .047 [1.20mm])
29= raised SMD ("A" = .197 [5.00mm])
BALL DIAMETER FOR:
-29(RC) = .026 [0.66mm]
-30(SM) = .026 [0.66mm]

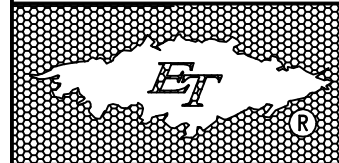
PIN DIAMETER FOR:
-70(ET) = .0177 [0.45mm]

* All Dimensions Are Nominal For A .050 [1.27mm] Pitch BGA Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 456
LEAD PITCH	= 1.27mm
GRID SIZE	= 26X26
PACKAGE SIZE	= 35.00mm SQ

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.

— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg.F
Santa Clara, Ca 95051
TEL:(408)982-0660
FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 04/04/03	REVISION: A	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Hanh Nguyen	ITEM: S-BGK-26-456-XX	DESCRIPTION: BPK-456-2BG026-YY
Scale 2:1	DO NOT SCALE DRAWING		